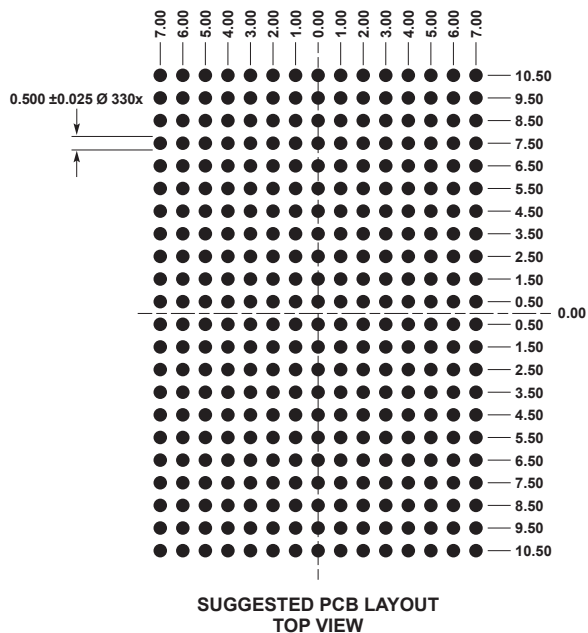
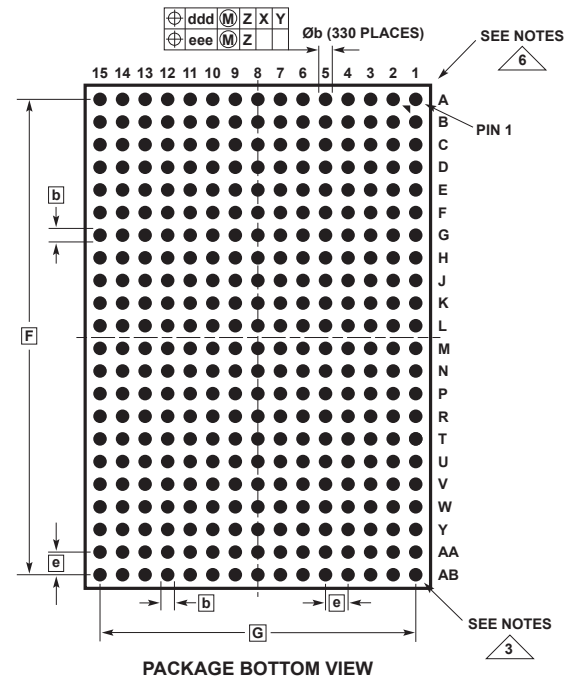
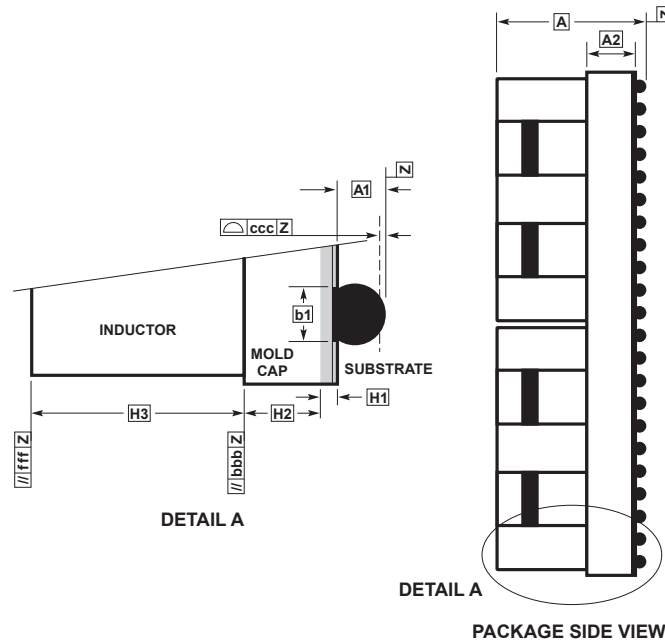
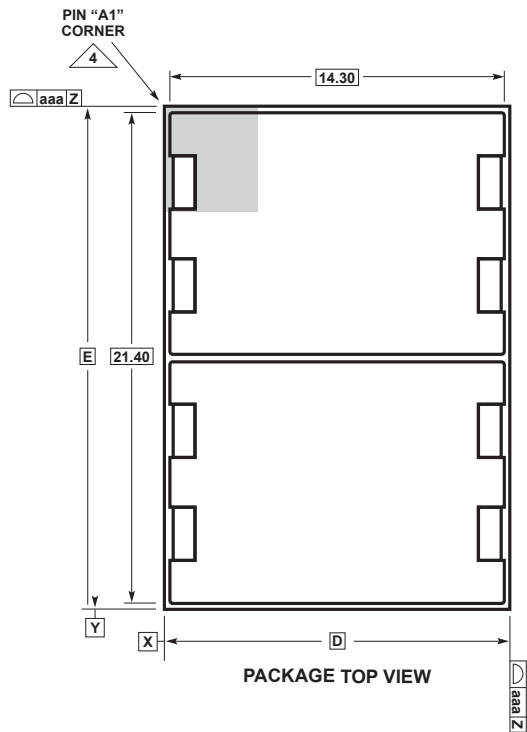


**BGA Package**  
**330-Lead (15mm × 22mm × 5.71mm)**  
 (Reference DWG # BC-330-2 Rev Ø)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	5.58	5.71	6.00	
A1	0.40	0.50	0.60	BALL HT
A2	1.72	1.82	1.92	
b	0.50	0.60	0.70	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D		15.00		
E		22.00		
e		1.00		
F		21.00		
G		14.00		
H1	0.27	0.32	0.37	SUBSTRATE THK
H2	1.45	1.50	1.55	MOLD CAP HT
H3			3.50	INDUCTOR HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.25	
eee			0.10	
fff			0.35	
<b>TOTAL NUMBER OF BALLS: 330</b>				

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY